Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An electronics unit, comprising:

a low multi-point metallic mount;

an insulating layer comprising a sintered electrically insulating polymer layer arranged on said mount;

a conductor track system comprising a sintered glass frit with a noble metal filling arranged on said insulating layer;

a resistance layer printed onto the polymer layer within one area of the conductor track system; and

electronic power components arranged on said conductor track system.

2. (Original) The electronics unit of claim 1, wherein said noble metal filling comprises one of a silver filling and a filling containing silver.

3. (Original) The electronics unit of claim 1, wherein said glass frit is a low melting-point glass frit.

4. (Original) The electronics unit of claim 2, wherein said glass frit is a low melting-point glass frit.

5. (Original) The electronics unit of claim 1, wherein said mount is made of a material from the group consisting of aluminum and an aluminum alloy.

6. (Original) The electronics unit of claim 1, wherein said mount comprises cooling ribs.

7. (Currently Amended) The electronics unit of claim 1, wherein said at least one power components comprise at least one of a power semiconductor ~~elements~~ element and a driver component ~~components~~.

8. (Currently Amended) The electronics unit of claim 1, further comprising at least one of an electrical and an electronic ~~components~~ component arranged on the conductor track system.

9. (Currently Amended) The electronics unit of claim 8, wherein said power components and said at least one of an electrical and an electronic component ~~components~~ are conductively connected to the conductor track system by one of soldering and bonding.

10. (Original) The electronics unit of claim 1, wherein said power components are conductively connected to the conductor track system by one of soldering and bonding.

11. (Original) The electronics unit of claim 1, wherein said electrically insulating polymer layer has a thickness of about >20 μm.

12. (Currently Amended) The electronics unit of claim 1, further comprising:

a further insulating layer comprising a sintered polymer arranged on said conductor track system and on one of said electronic power components;

a further conductor track system comprising a sintered glass frit with noble metal filling arranged on said further insulating layer; and

a further electronic power ~~components~~ component arranged on said further conductor track system.

13. (Withdrawn) A method for producing an electronics unit having a low multi-point metallic mount, an insulating layer comprising a sintered electrically insulating polymer layer arranged on the mount, a conductor track system comprising a sintered glass frit with a noble metal filling arranged on the insulating layer, and electronic power components arranged on the conductor track system, said method comprising the steps of:

applying the electrically insulating polymer layer to the mount;

drying and sintering the electrically insulating polymer layer in a temperature-controlled process;

applying the conductor track system to the polymer layer as a paste system comprising a low melting-point glass frit with noble metal filling;

drying and sintering the conductor track system in a temperature-controlled process; and

conductively arranging the electronic power components on the conductor track system.

14. (Withdrawn) The method of claim 13, wherein the temperature-controlled processes for sintering the polymer layer and for sintering the conductor track system are performed as a joint sintering process.

15. (Withdrawn) The method of claim 13, wherein said step of drying the polymer layer and drying the conductor track system is performed at a temperature of about 150°C.

16. (Withdrawn) The method of claim 13, wherein the temperature-controlled process for sintering the polymer layer is performed at a temperature of about 200°C.

17. (Withdrawn) The method of claim 16, wherein the temperature-controlled process for sintering the polymer layer is performed for about one hour.

18. (Withdrawn) The method of claim 13, wherein the temperature-controlled process for sintering the polymer layer is performed at a temperature of between about 450°C and 550°C.

19. (Withdrawn) The method of claim 13, wherein the temperature-controlled process for sintering the polymer layer is performed at a temperature of about 500°C.

20. (Withdrawn) The method of claim 13, wherein said step conductively arranging includes one of soldering, bonding, and adhesive bonding the electronic power components on the conductor track system.

21. (Withdrawn) A method for producing an electronics unit having a low multi-point metallic mount, an insulating layer comprising a sintered electrically insulating polymer layer arranged on the mount, a conductor track system comprising a sintered glass frit with a noble metal filling arranged on the insulating layer, and electronic power components arranged on the conductor track system, said method comprising the steps of:

applying a layer assembly comprising the electrically insulating polymer layer and the conductor track system which is arranged on the polymer layer to a flexible mount, the conductor track layer being applied as a paste system comprising a low melting-point glass frit with a noble metal filling;

drying the layer assembly on the flexible mount, in that the layer assembly together with the polymer layer on the mount is applied such that it rests on the mount

disconnecting the flexible mount from the layer assembly; and

sintering the layer assembly onto the mount in a temperature-controlled process.

22. (Withdrawn) The method of claim 21, wherein the temperature-controlled process for sintering the polymer layer is performed at a temperature of between about 450°C and 550°C.

23. (Withdrawn) The method of claim 21, wherein the temperature-controlled process for sintering the polymer layer is performed at a temperature of about 500°C.

24. (Withdrawn) The method of claim 21, further comprising the step of conductively arranging the electronic power components on conductor track system by one of soldering, bonding, and adhesive bonding the electronic power components on the conductor track system.